

## SG6841DZ3

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### Highly-Integrated Green-Mode PWM Controller

#### Qualification Data

#### Test Standards:

- ? Moisture Sensitivity: NA
- ? Thermal Impedance: 82
- ? Physical Dimensions: DIP
- ? ESD HBM: 3
- ? ESD MM: 250

| Attribute                                 | Value   | UOM     |
|---|---|---------|
| <b>General Information</b>                |   |         |
| Device Marking(TOP MARK)                  | <a href="#">SG6841DZ3</a><br><a href="#">B&amp;60&amp;4&amp;Z</a> |         |
| Family Code                               | 0GD   |         |
| Package Type                              | <a href="#">DIP</a>   |         |
| Package Description                       | 008,PLASTIC, MOLDED DIP   |         |
| Pin Count                                 | 8   |         |
| Maximum Reflow Temperature                | NA (thru hole)  |         |
| <b>Restriction of Hazardous Substance</b> |   |         |
| Standard Plating Finish                   | Matte Sn  |         |
| Base Metal/Leadframe Material             | Copper,Iron,Zinc,Phosphorus,Silver                                |         |
| Lead Pitch                                | 2540  |         |
| Minimum Lead Spacing                      | 760   |         |
| <b>Die Fabrication</b>                    |   |         |
| Fabrication Process Identifier            | BSMC  |         |
| <b>Package Assembly*</b>                  |   |         |
| Plating Finish Layer Thickness            | 8.0um - 13um  |         |
| Thermal Impedance (Theta JA)              | 82  | °C/Watt |
| Moisture Sensitivity                      | NA  |         |
| <b>Electrical Test</b>                    |   |         |
| ESD Human Body Model (HBM)                | 3   | V       |
| ESD Machine Model (MM)                    | 250   | V       |

\*If an attribute is listed twice, either can be used on the part.